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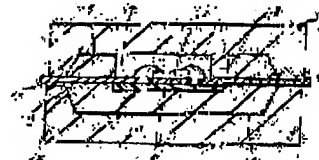
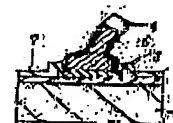
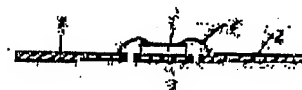
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### (54) RESIN-SEALED SEMICONDUCTOR DEVICE AND MANUFACTURE THEREOF

#### (57)Abstract:

PURPOSE: To manufacture a device wherein the EP-ROM package is plasticized, by forming a resin-molded form which is opened above the chip to include a lead frame, and constructing a resin-sealed type package wherein a transparent glass cover portion is bonded to the opening portion.

CONSTITUTION: A divided Si semiconductor chip 1 is connected to the tab 3 of a lead frame, which consists of a lead 2 and the tab 3. then, bonding is performed between the Al electrode exposed on the chip surface and each lead 2 with an Al wire 4. Next, an insulating protective film 6 of alumina is formed on the surface of the wire 4. And a plate 8 is bonded to the under surface of the frame 2, 3. Further, the lead frame is loaded into molds 9, 10, and resin 11 is molded to form a primary resin-molded form 13. A transparent glass plate 14 is inserted in the opening of the molded form 13 taken out from the molds, and adhesive sealing is performed. The molded form 13 is again placed in the molds, and a secondary resin-molded form 19 is formed by resin molding. And the lead is separated at the projected portion of the lead frame of the molded form 19 taken out.



#### LEGAL STATUS

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